



Material Content Data Sheet



Sales Product Name		TLE7259-3GE		Issued		9. January 2019			
MA#		MA002213834							
Package		PG-DSO-8-16		Weight*		83.31 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.228	2.67	2.67	26739	26739	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108		
		non noble metal	zinc	7440-66-6	0.036	0.04		430	
		non noble metal	iron	7439-89-6	0.717	0.86		8609	
wire	noble metal	non noble metal	copper	7440-50-8	29.121	34.96	35.87	349552	358699
		noble metal	gold	7440-57-5	0.213	0.26	0.26	2557	2557
		organic material	carbon black	1333-86-4	0.097	0.12		1159	
encapsulation	plastics	epoxy resin	-	4.443	5.33		53330		
		inorganic material	silicondioxide	60676-86-0	43.753	52.52	57.97	525188	579677
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9769	9769	
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7805	7805	
glue	plastics	acrylic resin	-	0.270	0.32		3246		
		noble metal	silver	7440-22-4	0.959	1.15	1.47	11508	14754
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com